ALTEK ELECTRONICS, INC.

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Bare Printed Circuit Board Artwork Request

This form defines most of the criteria and considerations required when creating artwork for a bare PCB.
Please complete the following with as much applicable information as possible.

Return completed forms to Sabrina Beck at sabrina.beck@altekelectronics.com **or to the address listed above.**

Project Information:

Customer Name: ____

Project Name/Description: ______________________________________

Assembly P/N: ____________________ Rev: __________

Bare PCB P/N: ____________________ Rev: __________

Primary Design Input: *(Check off if item will be provided)*

☐ Dimensioned board outline drawing (with all appropriate tolerances) including:
  - Mounting holes
  - Height restrictions
  - Connectors
  - Tooling holes
  - Critical component locations
  - Restricted areas (hardware, heatsinks, etc)
  - Fiducials
  - Edge clearance
  - Special features

☐ Schematic diagram.

☐ Bill of materials (manufacturer, P/N, and reference designators matching the schematic symbols)

☐ Component part library (cross reference schematic symbols to pcb footprints).

☐ CAD software specific files (eg. Cadstar files: .cdo, .sch, .pcb, .col, .sel, .sym, .cmp, .lib)

(Complete all fields)

Board Type: ☐ Rigid ☐ Flex ☐ Rigid-Flex combination

Board Material: ☐ Generic FR4 ☐ Other (manufacturer & p/n): ____________________

Board Thickness: ____

Conductor Finish: ☐ Lead HASL ☐ Lead Free HASL ☐ Immersion Silver ☐ Immersion Gold (ENIG)

☐ Other: ____

Surface Finish: ☐ SMOBC ☐ None ☐ Other: ____________

Select one: ☐ Through-Hole ☐ Surface Mount ☐ Mixed technology

Component placement: ☐ Not Restricted ☐ Fixed (If fixed must submit drawing.)

Component orientation requirements: ______________________________

Are connector pin assignments fixed: ☐ Yes ☐ No

Are gate/pin swapping allowed: ☐ Yes ☐ No

Thieving allowed for copper balance: ☐ Yes ☐ No

Are parts allowed on both sides: ☐ Never ☐ If necessary ☐ Only in certain areas (provide dwg)

Test Considerations: *(Complete fields where applicable)*

Test point requirements: ______________________________
ICT requirements: ______________________________
HiPot requirements: ______________________________
Shock/Vibe requirements: ______________________________

Design Technology: *(Complete fields where applicable)*

Special plane requirements: ______________________________
Special ground pattern requirements: ______________________________
Mounting hole connections (ground, specific nets): ______________________________
Minimum via size (signal, power): ______________________________
Clearance of traces to board outline: ______________________________
Clearance of components to board outline: ______________________________
Pastemask clearance requirements: ______________________________
Creepage and clearance requirements: ______________________________
Trace width/clearance requirements: ______________________________
Heat sinking areas or requirements: ______________________________

Check off if specified item is in design.

☐ Micro vias ☐ Blind vias ☐ Plugged vias ☐ Buried vias
☐ HDI ☐ BGA ☐ Fine-pitch components

Other special technologies: ______________________________

Solder Mask: *(Complete fields where applicable)*

Sides: ☐ Top ☐ Bottom ☐ Both
Color: ______________________________
Special clearance requirements: ______________________________
Tented vias: ☐ Yes ☐ No

Special Considerations: *(Complete fields where applicable)*

Hole plating requirements: ______________________________
Controlled impedance requirements: ______________________________
Routing requirements: ______________________________
Trace requirements (eg. corner types, 90/45 degree, radial): ______________________________
High voltage requirements: ______________________________
High current requirements: ______________________________
High speed requirements: ______________________________
RF requirements: ______________________________
Panel requirements: ______________________________

Nomenclature: *(Complete fields where applicable)*

Top silk requirements: ______________________________

Bottom silk requirements: ______________________________

Copper etch requirements: ______________________________

Silkscreen polarity/pin 1 markings: ☐ Yes ☐ No

Test pad reference designators: ☐ Top ☐ Bottom ☐ Both ☐ None

Layer Considerations: *(Complete fields where applicable)*

#	*Description*	*Type*	*Copper Weight*
1	____________	☐ Signal ☐ Plane ☐ Split	☐ 1 oz. ☐ 2 oz. ☐ other: _______
2	____________	☐ Signal ☐ Plane ☐ Split	☐ 1 oz. ☐ 2 oz. ☐ other: _______
3	____________	☐ Signal ☐ Plane ☐ Split	☐ 1 oz. ☐ 2 oz. ☐ other: _______
4	____________	☐ Signal ☐ Plane ☐ Split	☐ 1 oz. ☐ 2 oz. ☐ other: _______
5	____________	☐ Signal ☐ Plane ☐ Split	☐ 1 oz. ☐ 2 oz. ☐ other: _______
6	____________	☐ Signal ☐ Plane ☐ Split	☐ 1 oz. ☐ 2 oz. ☐ other: _______
7	____________	☐ Signal ☐ Plane ☐ Split	☐ 1 oz. ☐ 2 oz. ☐ other: _______
8	____________	☐ Signal ☐ Plane ☐ Split	☐ 1 oz. ☐ 2 oz. ☐ other: _______
9	____________	☐ Signal ☐ Plane ☐ Split	☐ 1 oz. ☐ 2 oz. ☐ other: _______
10	____________	☐ Signal ☐ Plane ☐ Split	☐ 1 oz. ☐ 2 oz. ☐ other: _______

Other Requirements: *(Indicate any other requirements or considerations not listed above)*